# Product End-of-Life Disassembly Instructions

## Product Category: Monitors and Displays

### Marketing Name / Model
[List multiple models if applicable.]

HP LD4245tm 42-inch Interactive LED Digital Signage Display

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**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm Main PCBA, Power PCBA</td>
<td>2</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries Remotecontroller(2EA), Main Board(1EA)</td>
<td>3</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td>1</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>Power cord, DP cable, RGB cable, IR cable, HDMI cable</td>
<td>5</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td>0</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>
Components, parts and materials containing refractory ceramic fibers | 0
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Components, parts and materials containing radioactive substances | 0

### 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1 Screw driver of &quot;+&quot; type</td>
<td></td>
</tr>
<tr>
<td>Description #2</td>
<td></td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

### 3.0 Product Disassembly Process

#### 3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Put the Monitor on the clean vinyl, Unlock Screw 10EA, disassemble bottom metal fixer R/L
2. Unlock Screw 24EA, disassemble backcover
3. Detach Tapes.
4. Remove screw 8EA, Disassemble Control PCB assy, Main PCB assy.
5. Remove Screw 8EA & Disassemble AC socket cover.
6. Remove Screw 15EA.
7. Remove Screw 9EA, Disassemble Metals
8. Remove Screw 2EA, Disassemble Mold cover
9. Detach the tapes, pads & Disassemble Module
10. Remove screw 16EA & Disassemble corner metal fixer 4EA.
11. Remove screw 16EA & Disassemble corner mold bracket 4EA.
12. Disconnect FFC Cable, and push Touch PCB to one side
13. Disassemble AL Bar, IR filter, Touch PCB
14. Disconnect FFC Cable from wafer of Touch PCB
15. Remove screw 9EA, Disassemble AV Shield, Heat sink, Coin Battery
16. Cover is strongly connected with wire, so it cannot be separated from remote controller
17. 

#### 3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

Pls. refer the attached:
6 Product Disassembly instructions for End-of-Life

Product Identification:

<table>
<thead>
<tr>
<th>Marketing Name / Model</th>
<th>Description</th>
</tr>
</thead>
<tbody>
<tr>
<td>LD4245tm</td>
<td>42” HP LED Touch monitor</td>
</tr>
</tbody>
</table>

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of products to remove components and materials requiring selective treatment.

1. Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Screw driver</td>
<td></td>
</tr>
</tbody>
</table>

2. Product disassembly Process

2.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

2.2 OPTIONAL: Depending upon the complexity of the disassembly process, a graphic depicting the locations of items contained within the product which require selective treatment (with descriptions and arrows identifying locations) can be inserted below:

2.3 How to describe the basic steps to disassembly a components.

   1) Provide a picture of disassembly process
   2) All the screws are showed in the picture
   3) All the PCBAs are showed in the picture
   4) LCD panel are showed in the picture
   5) All the accessories like remote controller, batteries, and cables are showed in the picture

3. Related regulations: WEEE directive, EPEAT
Fig. 1  Put the Monitor on the clean vinyl
Unlock Screw 10EA, disassemble Bottom metal fixer R/L

Fig. 2  Unlock Screw 24EA, disassemble backcover
Fig. 3  Detach Tapes

Fig. 4  Remove screw 8EA & Disassemble Main PCB, Control PCB Assy
Fig. 5  Remove Screw 8EA & Disassemble AC socket cover

Fig. 6  Remove Screw 15EA
Fig. 7  Remove Screw 9EA, Disassemble Metals

Fig. 8  Remove Screw 2EA, Disassemble Mold cover
Fig. 9   Detach the tapes, pads & Disassemble Module

Fig. 10   Remove screw 16EA & Disassemble corner metal fixer 4EA
Fig. 11  Remove screw 16EA & Disassemble corner mold bracket 4EA

Fig. 12  Disconnect FFC Cable, and push Touch PCB to one side

Fig. 13  Disassemble AL Bar, IR filter, Touch PCB
Fig. 14  Disconnect FFC Cable from wafer of Touch PCB

Fig. 15  Remove screw 9EA, Disassemble AV Shield, Heat sink, Coin Battery
Fig. 16  Remove screw 2EA of Control, and Disassemble the control pcb

Fig. 17  Cover is strongly connected with wire, so it cannot be separated from remote controller